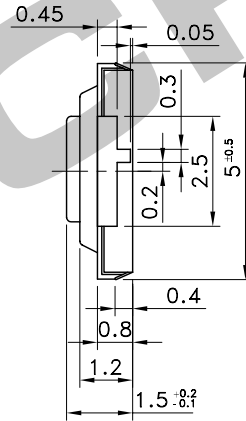
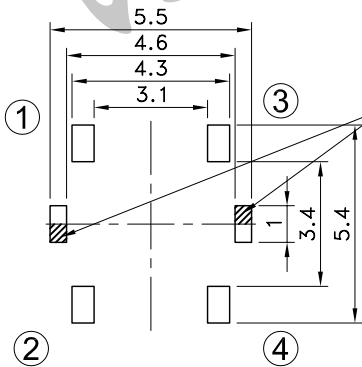


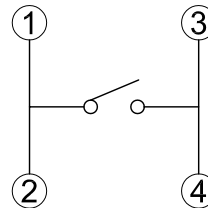
P.C.B TERMINAL POSITION



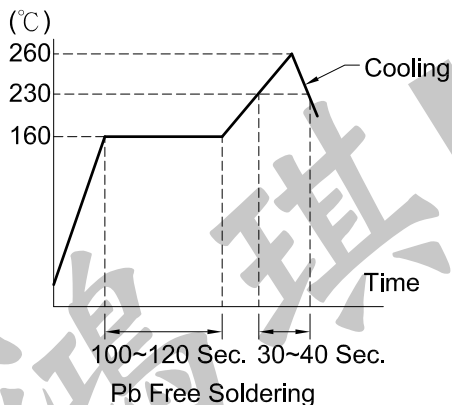
CIRCUIT ARRANGEMENT



GROUND PIN:
The thickness of cream solder:150~200 μ
We recommend to connect the GND land shown in the switch spec. with the GND of your P.C.B for withstanding electric-static discharge.



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

- | | |
|-----------------------------|---|
| 1. Rating | : DC 15V 20mA |
| 2. Contact Resistance | : 50mΩ Max. |
| 3. Insulation Resistance | : 50MΩ Min. at DC 100V |
| 4. Dielectric Strength | : AC 250V For 1 Minute |
| 5. Operating Force | : 260±50gf |
| 6. Stroke | : 0.25 ±0.1 mm |
| 7. Life | : 200,000 Cycles |
| 8. Taping | : 5,000 Pcs/Reel |
| 9. Reflow Soldering Profile | : According Reflow Profile Max. 2 Times |

REVISION:		DATE:		REVISION:		DATE:	
UNIT:mm		THIRD ANGLE PROJECTION METHOD		TOL. UNLESS OTHERWISE STATED:±0.3		CODE NO.:HCH-137-4	
ISSUED		CONFIRMED		HCH HORNG CHIH ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司		PART NO. STS-05-B	
<i>John</i> 2007.05.18		<i>Elvis</i> 2007.05.18					